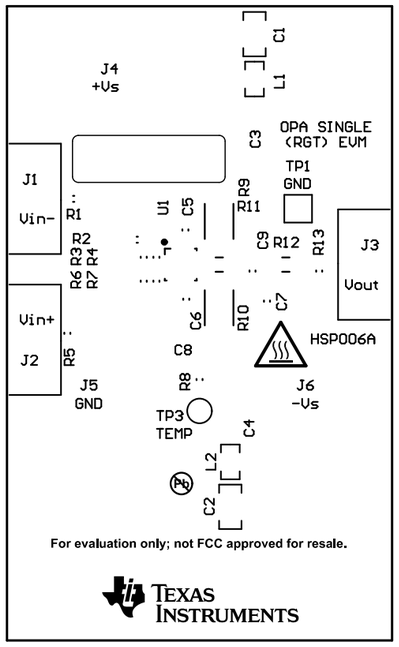
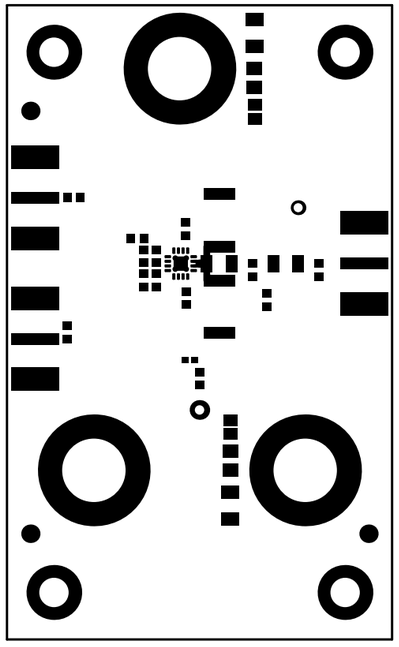
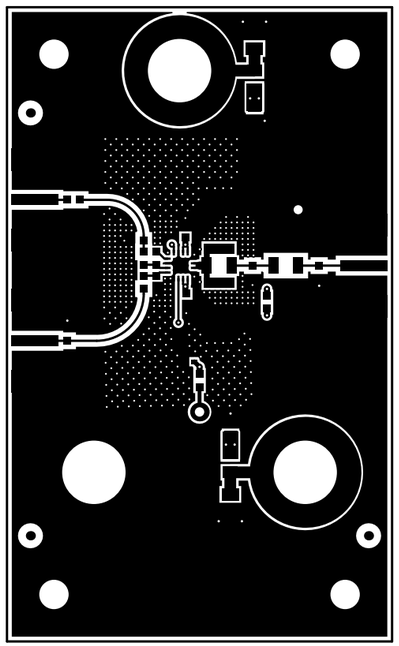


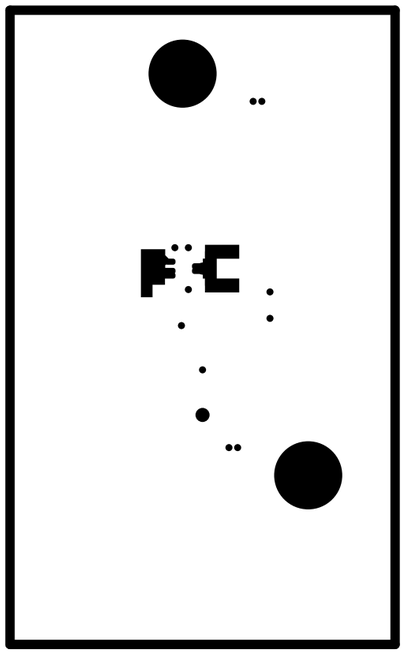
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: HSP006	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: N/A		
PLOT NAME = Top Overlay	GENERATED : 7/24/2017 11:03:09 AM		TEXAS INSTRUMENTS



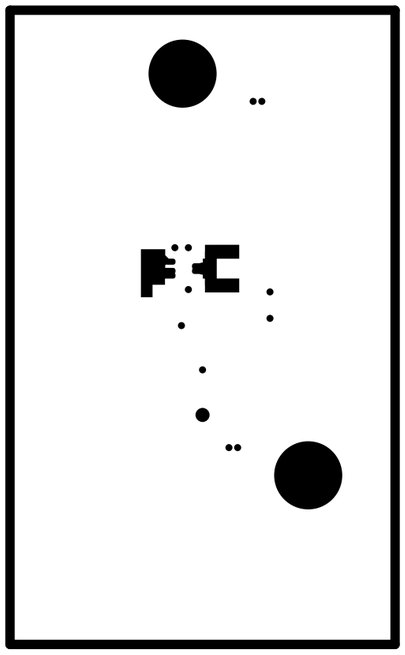
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: HSP006	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: N/A		
PLOT NAME = Top Solder Mask	GENERATED : 7/24/2017 11:03:10 AM		TEXAS INSTRUMENTS



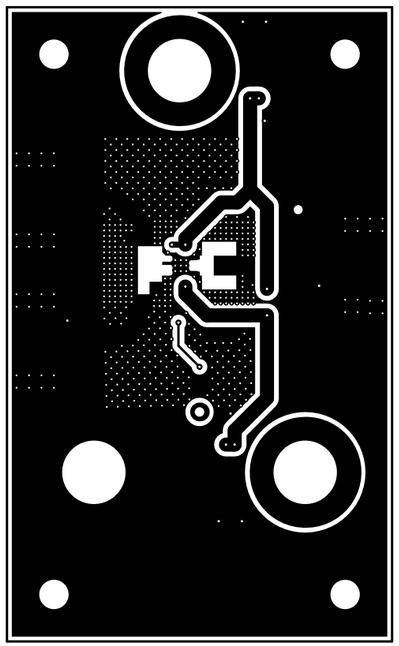
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: HSP006	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Top Layer L1	TID #: N/A		
PLOT NAME = Top Layer L1	GENERATED : 7/24/2017 11:03:10 AM		TEXAS INSTRUMENTS



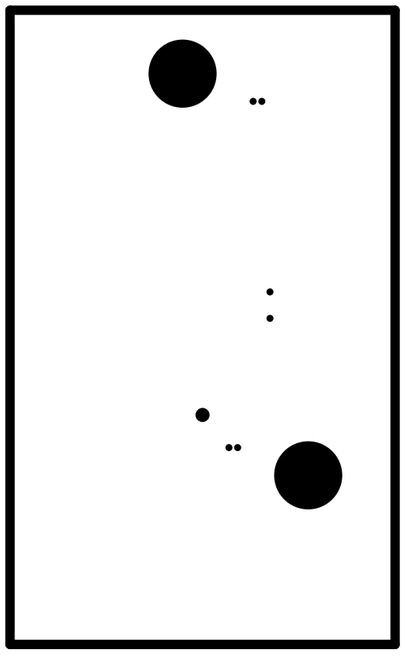
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: HSP006	REV: A	SVN REV: Not In VersionControl
LAYER NAME = GND Plane L2	TID #: N/A		
PLOT NAME = GND Plane L2	GENERATED : 7/24/2017 11:03:11 AM		TEXAS INSTRUMENTS



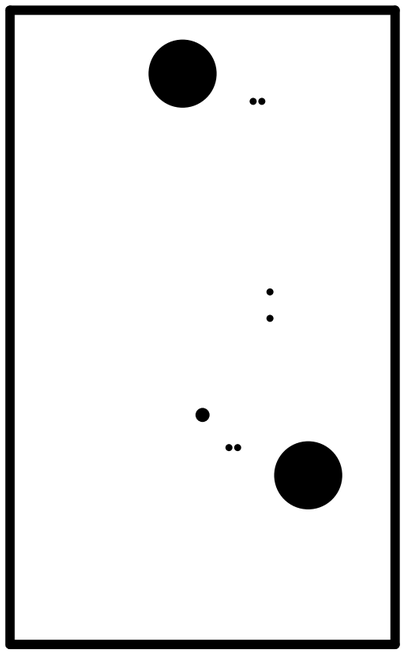
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: HSP006	REV: A	SVN REV: Not In VersionControl
LAYER NAME = GND Plane L3	TID #: N/A		
PLOT NAME = GND Plane L3	GENERATED : 7/24/2017 11:03:12 AM		TEXAS INSTRUMENTS



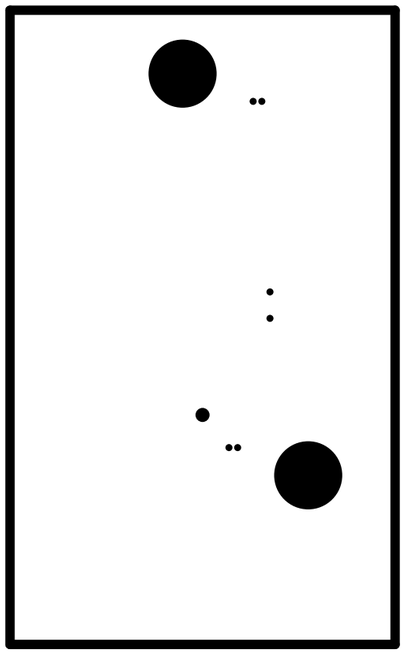
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: HSP006	REV: A	SVN REV: Not In VersionControl
LAYER NAME = GND/Signal L4	TID #: N/A		
PLOT NAME = GND/Signal L4	GENERATED : 7/24/2017 11:03:13 AM		TEXAS INSTRUMENTS



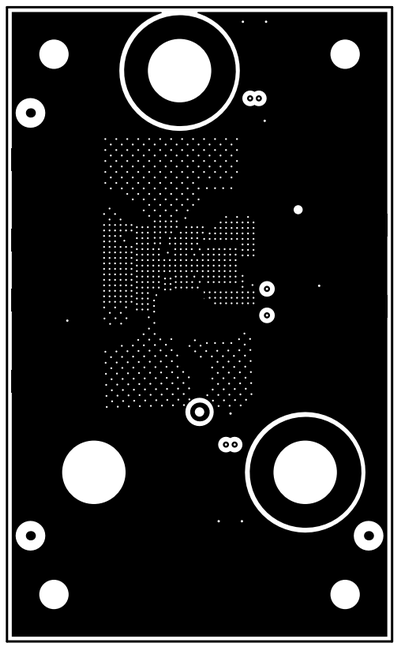
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: HSP006	REV: A	SVN REV: Not In VersionControl
LAYER NAME = GND Plane L5	TID #: N/A		
PLOT NAME = GND Plane L5	GENERATED : 7/24/2017 11:03:14 AM		TEXAS INSTRUMENTS



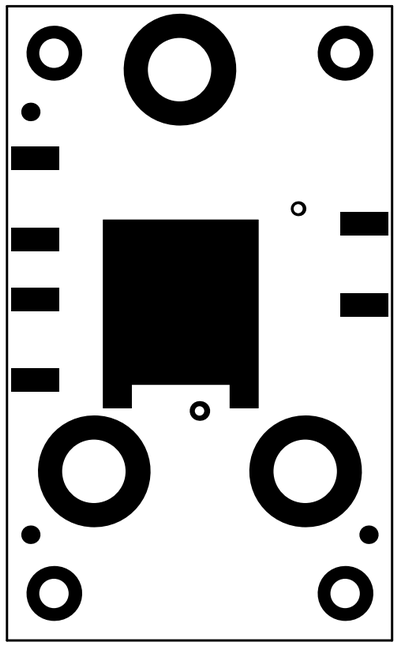
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: HSP006	REV: A	SVN REV: Not In VersionControl
LAYER NAME = GND Plane L6	TID #: N/A		
PLOT NAME = GND Plane L6	GENERATED : 7/24/2017 11:03:14 AM		TEXAS INSTRUMENTS



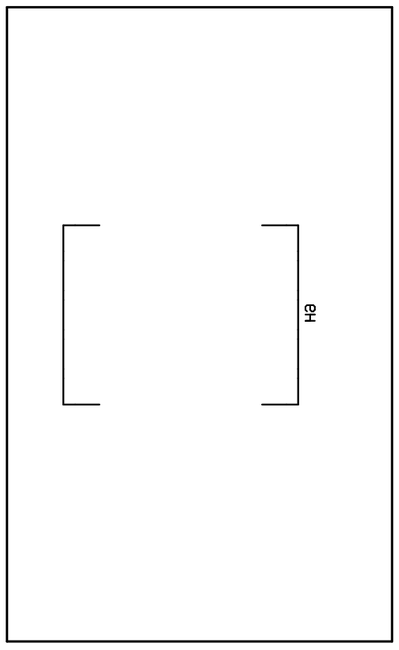
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: HSP006	REV: A	SVN REV: Not In VersionControl
LAYER NAME = GND Plane L7	TID #: N/A		
PLOT NAME = GND Plane L7	GENERATED : 7/24/2017 11:03:15 AM		TEXAS INSTRUMENTS



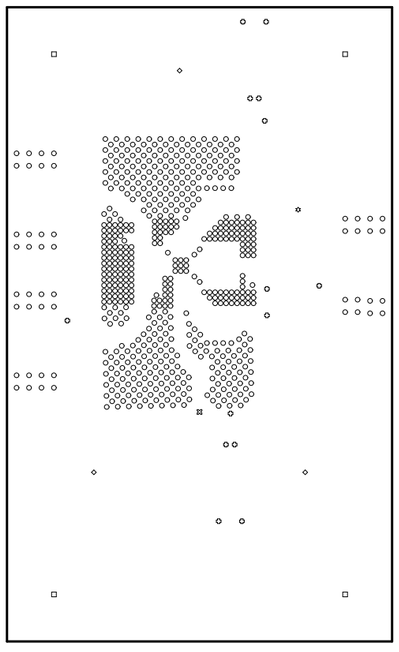
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: HSP006	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Bottom Layer L8	TID #: N/A		
PLOT NAME = Bottom Layer L8	GENERATED : 7/24/2017 11:03:16 AM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: HSP006	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: N/A		
PLOT NAME = Bottom Solder Mask	GENERATED : 7/24/2017 11:03:17 AM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: HSP006	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: N/A		
PLOT NAME = Bottom Overlay	GENERATED : 7/24/2017 11:03:17 AM		TEXAS INSTRUMENTS

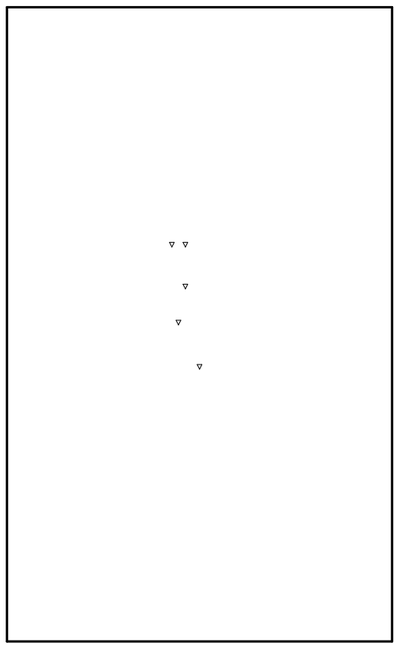


Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
○	594	7.87mil (0.200mm)	PTH	Round	Top Layer L1 - Bottom Layer L8	
⌖	14	10.00mil (0.254mm)	PTH	Round	Top Layer L1 - Bottom Layer L8	
✡	1	38.50mil (0.978mm)	PTH	Round	Top Layer L1 - Bottom Layer L8	
⊠	1	40.00mil (1.016mm)	PTH	Round	Top Layer L1 - Bottom Layer L8	
□	4	125.00mil (3.175mm)	PTH	Round	Top Layer L1 - Bottom Layer L8	
◇	3	270.00mil (6.858mm)	PTH	Round	Top Layer L1 - Bottom Layer L8	
	617 Total					

7.87mil (0.200mm) Holes L1 to L8 to be to be plugged with thermal/electrical conductive epoxy of manufacturers choice. Plugged vias to be plated after plugging to present flat surface to device U1 on L1 and H9 on L8, no potholes.

7.87mil (0.200mm) Holes L5 to L8 to be to be plugged with thermal/electrical conductive epoxy of manufacturers choice. Plugged vias to be plated after plugging to present flat surface to device H9, no potholes.

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: HSP006	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: N/A		
PLOT NAME = Drill Drawing L1 - L8	GENERATED : 7/24/2017 11:03:18 AM		TEXAS INSTRUMENTS

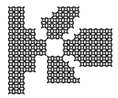


Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
∇	5	10.01mil (0.254mm)	PTH	Round	Top Layer L1 - GND/Signal L4	
	5 Total					

7.87mil (0.200mm) Holes L1 to L8 to be to be plugged with thermal/electrical conductive epoxy of manufacturers choice. Plugged vias to be plated after plugging to present flat surface to device U1 on L1 and H9 on L8, no potholes.

7.87mil (0.200mm) Holes L5 to L8 to be to be plugged with thermal/electrical conductive epoxy of manufacturers choice. Plugged vias to be plated after plugging to present flat surface to device H9, no potholes.

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: HSP006	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: N/A		
PLOT NAME = Drill Drawing L1 - L4	GENERATED : 7/24/2017 11:03:19 AM		TEXAS INSTRUMENTS

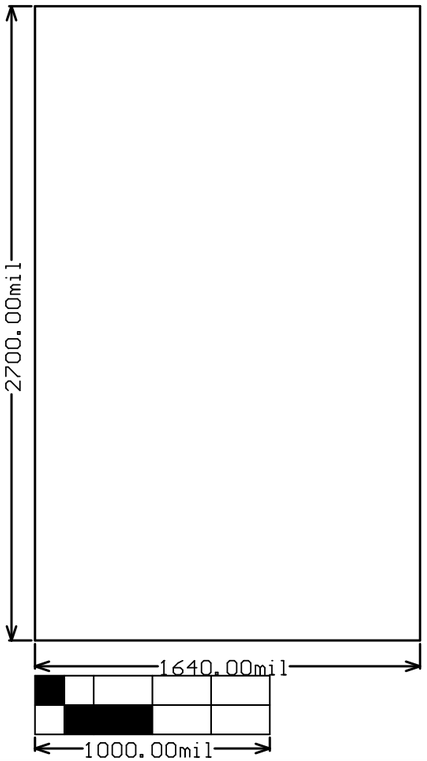


Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
⌑	174	7.87mil (0.200mm)	PTH	Round	GND Plane L5 - Bottom Layer L8	
	174 Total					

7.87mil (0.200mm) Holes L1 to L8 to be to be plugged with thermal/electrical conductive epoxy of manufacturers choice. Plugged vias to be plated after plugging to present flat surface to device U1 on L1 and H9 on L8, no potholes.

7.87mil (0.200mm) Holes L5 to L8 to be to be plugged with thermal/electrical conductive epoxy of manufacturers choice. Plugged vias to be plated after plugging to present flat surface to device H9, no potholes.

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: HSP006	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: N/A		
PLOT NAME = Drill Drawing L5 - L8	GENERATED : 7/24/2017 11:03:20 AM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: HSP006	REV: A	SVN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: N/A		
PLOT NAME = Board Dimensions	GENERATED : 7/24/2017 11:03:21 AM		TEXAS INSTRUMENTS